



## BONDING WITH NANO STRUCTURED MULTI LAYERS

### ナノ構造マルチレイヤーによるボンディング

- fast heating rate: up to 109 K/s
- high reaction speed: up to 30 m/s
- reaction temperature: 2000 °C

In Cooperation with:



## SCREEN PRINTING FOR WAFER BONDING

### MEMSパッケージングおよびウエハ接合用スクリーン印刷

- 736 x 736 mm standard frame
- unique vision alignment system
- Fully automatic vision system for precise, repeatable printing
- lateral: 190 µm – 150 mm
- vertical: 10 µm – 1 mm

In Cooperation with:

